CLAIMS

[1] An electronic component packaging sheet having a surface conductive layer formed on a surface on at least one side of a substrate sheet, wherein

the substrate sheet comprises a styrene-conjugated diene block copolymer (A), a polystyrene resin (B), and a high impact polystyrene resin (C), the components having the following weight-average molecular weights (Mw):

component (A): Mw = 80,000 to 220,000;

component (B): Mw = 200,000 to 400,000;

component (C): Mw = 150,000 to 210,000;

the surface conductive layer comprises an acrylic copolymer resin (D) and carbon nanotubes (E),

the glass transition temperature Tg of the acrylic copolymer resin (D) in the surface conductive layer is 25 to 80 °C, and

the substrate sheet is formed of a resin composition comprising 29 to 65 mass% component (A), 51 to 15 mass% component (B) and 20 to 9 mass% component (C).

[2] The electronic component packaging sheet of claim 1, wherein the peak molecular weight by GPC of polymer blocks of styrenic monomers in component (A) is in the range of 30,000 to 120,000; and a half-width of a molecular weight distribution curve of the polymer blocks of the styrenic monomers is in the range of 0.8 to 1.25.

[3] The electronic component packaging sheet of claim 1 or 2, wherein the rubber component in a graft rubber in component (C) is a diene rubber monomer chosen from the group consisting of 1,3-butadiene (butadiene), 2-methyl-1,3-butadiene (isoprene), 2,3-dimethyl-1,3-butadiene, 1,3-pentadiene, 1,3-hexadiene and 2-methylpentadiene, or a thermoplastic elastomer of a styrene-conjugated diene block copolymer wherein the diene component is at least 50 mass%.

[4] The electronic component packaging sheet of any one of claims 1 to 3, wherein the particle size of the graft rubber in component (C) is ϕ 2.0 to 3.0 μm, and the proportion of rubber in the graft rubber in the substrate sheet is 0.75 to 1.90 mass%.

[5] The electronic component packaging sheet of any one of claims 1 to 4, wherein the melt tension of the substrate sheet at 220 °C is 10 to 30 mN.

[6] The electronic component packaging sheet of any one of claims 1 to 5, wherein the carbon nanotubes in the surface conductive layer are multiwall carbon nanotubes of diameter 3 to 15 nm and length 0.5 to 3 μm, wherein the amount of the multiwall carbon nanotubes contained in the surface conductive layer is 3 to 10 mass%.

[7] The electronic component packaging sheet of any one of claims 1 to 6, wherein the particle size in an aqueous dispersion of the acrylic copolymer resin (D) in the surface conductive layer is 80 to 350 nm.

[8] The electronic component packaging sheet of any one of claims 1 to 7, wherein the surface resistance of a molded article with a draw ratio for thermoforming of 1.5 to 3 times is on the order of 10^5 Ω to 10^7 Ω.

[9] The electronic component packaging sheet of any one of claims 1 to8, wherein the coefficient of static friction of the conductive layer formed on the surface of the substrate sheet is at least 0.85 and at most 2.50, and the coefficient of kinetic friction is at least 0.85 and at most 2.50.

[10] A method for producing the electronic component packaging sheet of any one of claims 1 to 9, comprising steps of:

preparing a mixed dispersion by mixing the aqueous dispersion of an

acrylic copolymer with a dispersion of carbon nanotubes obtained by primary dispersion in a bead mill of carbon nanotubes in an aqueous solution of a sulfonic acid type dispersant having aromatics in the molecule, and secondary dispersion in an ultrasonic dispersion; and

applying the mixed dispersion onto at least one surface of the substrate sheet.

[11] A method for manufacturing a molded article by thermoforming the electronic component packing sheet of any one of claims 1 to 9.

[12] The method for manufacturing a molded article of claim 11, obtaining an embossed carrier tape.